Storage Temperature	T_{stg}

ORDERING INFORMATION

J OC T Y12 J -D6P/S /

Characteristics Curves

FIG.1: Max. Allowable LED Forward Current vs. Ambient Temperature

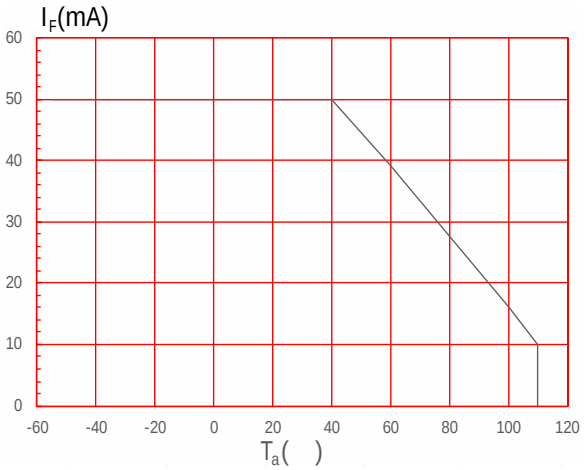


FIG.2: Collector Power Dissiption vs. Ambient Temperature

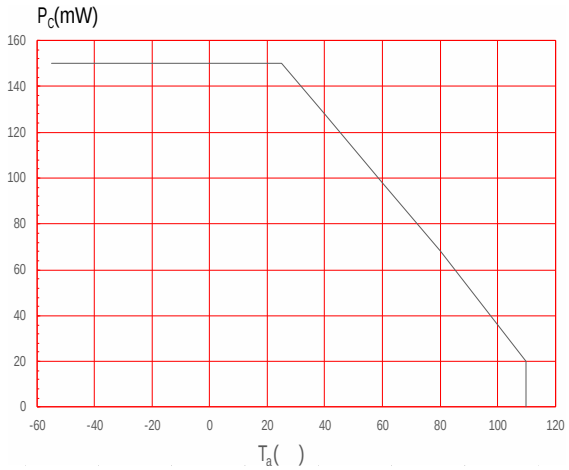


FIG.3: Forward Current vs. Forward Voltage

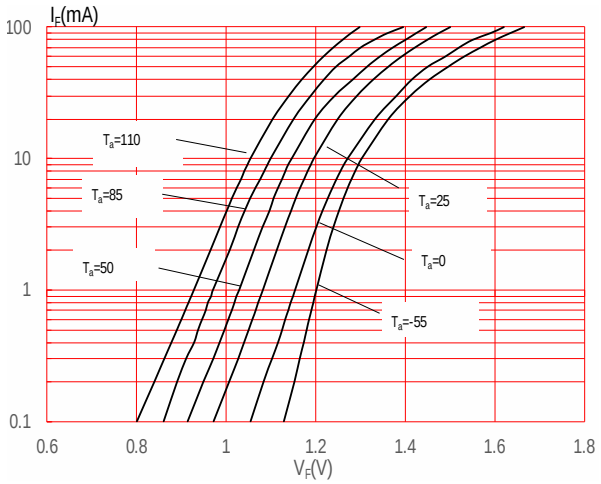
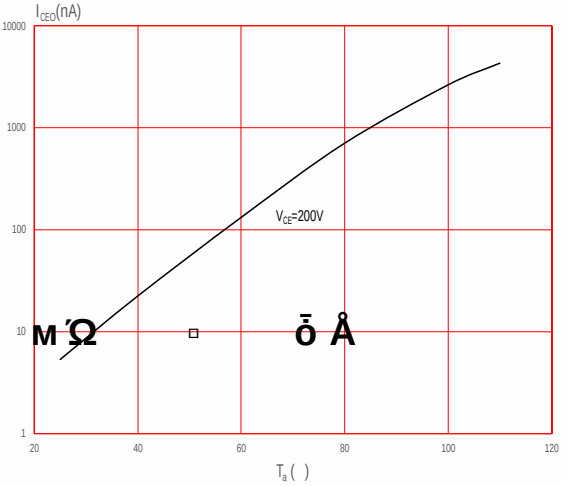


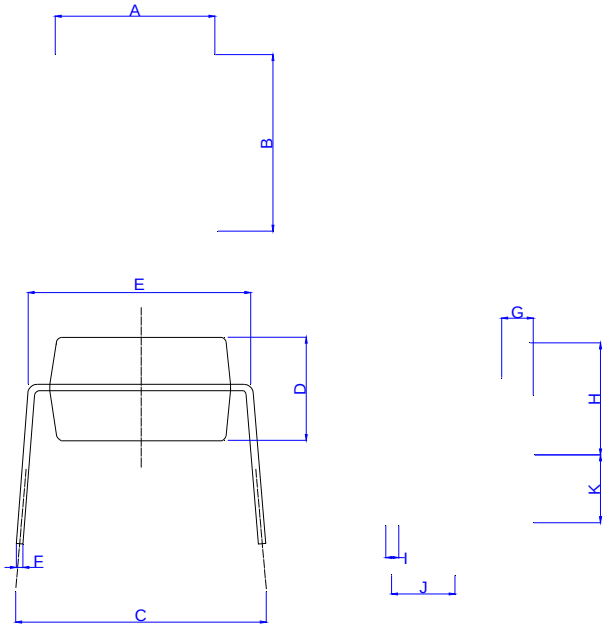
FIG.4: Collector Dark Current vs. Ambient Temperature



Test Circuits

Package Dimension (Unit: mm)

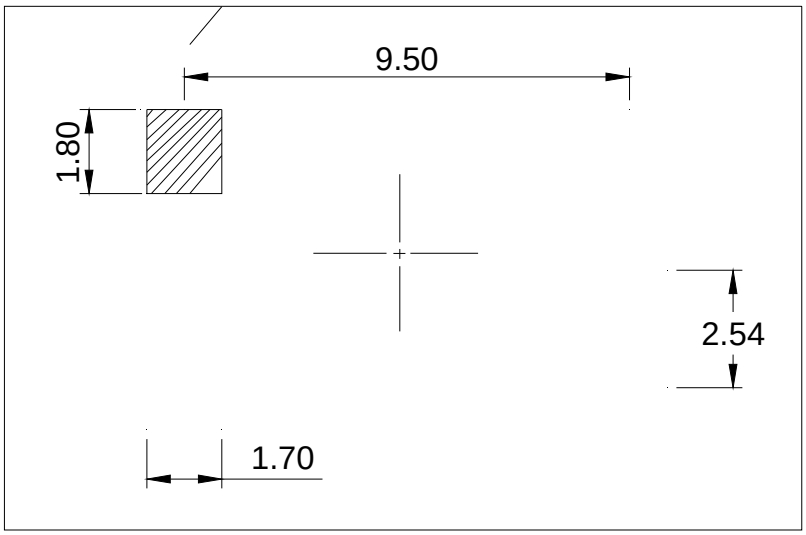
Standard DIP Type:

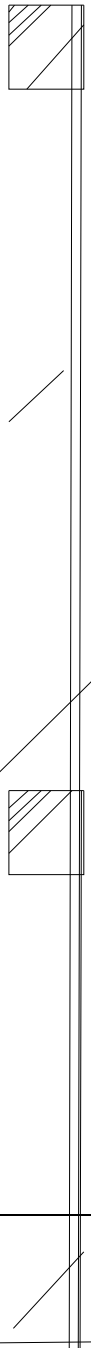


Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.20		6.60	0.244		0.260
B	6.92		7.32	0.272		0.288
C	7.150	.	8.95			
D	3.20		3.60	0.126		0.142
E	7.32		7.92	0.288		0.312
F						
G	1.15		1.35	0.045		0.053
H	3.90		4.50	0.154		0.177
I						
J						
K						

RECOMMENDED SOLDER MASK (Dimensions in mm unless otherwise stated)

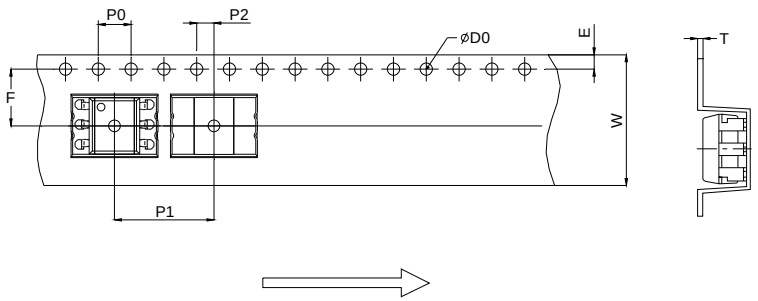
Option SMD





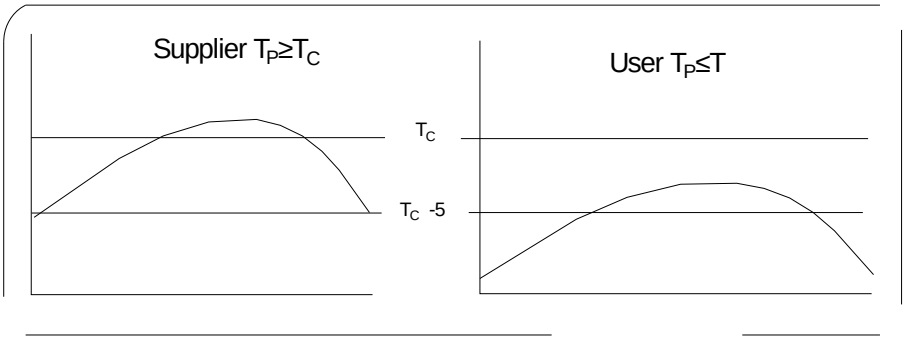
CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

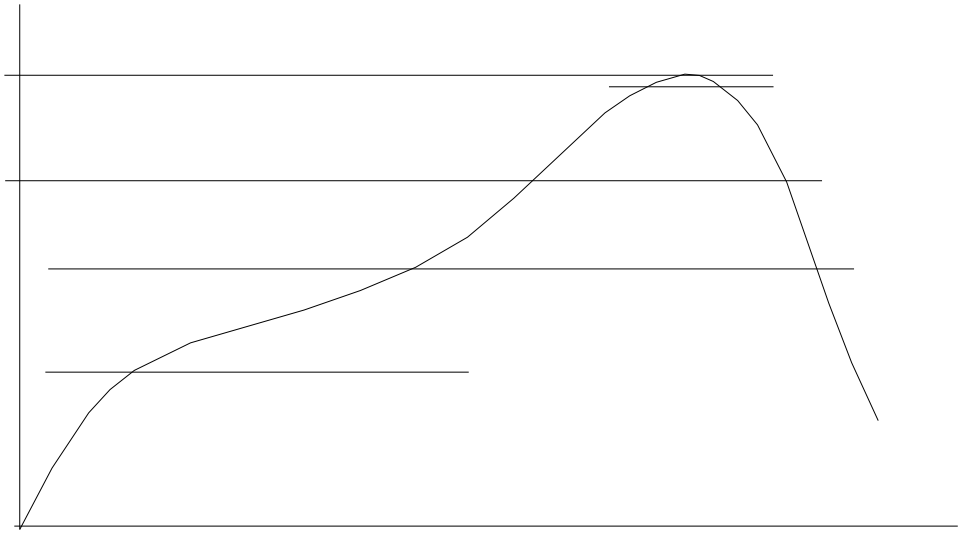
Option S



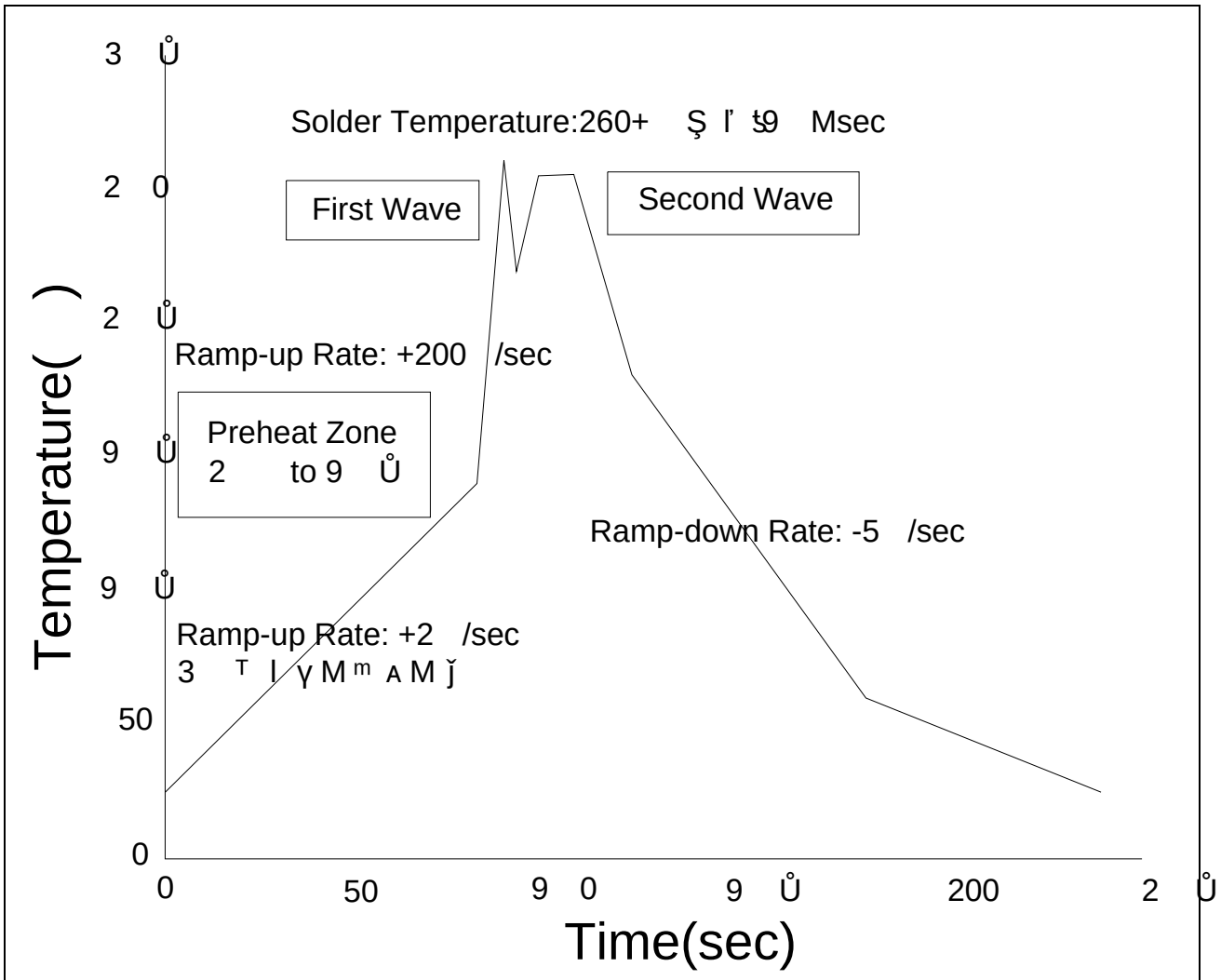
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.60		0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	11.90	12.00	12.10	0.469	0.472	0.476
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
T	0.35	0.40	0.45	0.014	0.016	0.018
W	15.70	16.00	16.30	0.618	0.630	0.642

REFLOW INFORMATION





WAVE SOLDERING



HAN M" ж ЯDERIN McY SOLDERIN M‿ þ ON	
Soldering Temperature	3 Ů
Soldering Time	3s max M

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.

2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum